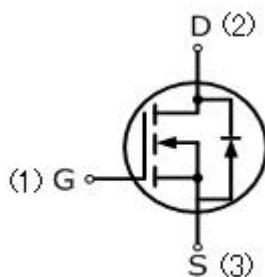


## PW065N08GS

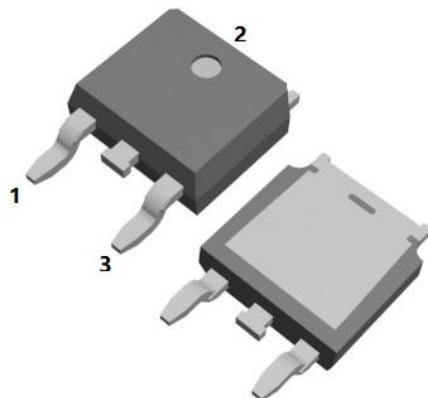
50 Amps, 85 Volts N-CHANNEL MOSFET

### FEATURE

- 50A, 85V,  $R_{DS(ON)MAX}=6.5\text{m}\Omega$  @  $V_{GS}=10\text{V}/20\text{A}$
- Low gate charge
- Low  $C_{iss}$
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



TO-252-2L



### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	PW065N08GS	UNIT
Drain-Source Voltage	$V_{DSS}$	85	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	50	A
Pulsed Drain Current(Note 1)	$I_{DM}$	200	
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	97	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	$T_L$	260	°C

### Thermal Characteristics

Parameter	Symbol	PW065N08GS	Units
Thermal resistance , Junction to Case	$R_{th(J-c)}$	1.5	°C/W
Maximum Power Dissipation	$T_c=25^\circ\text{C}$	$P_D$	83

Electrical Characteristics ( $T_c=25^\circ\text{C}$ ,unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	85	—	—	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=85\text{V}, \text{V}_{\text{GS}}=0\text{V}$	—	—	1	$\mu\text{A}$
Gate-Body Leakage Current,Forward	$\text{I}_{\text{GSSF}}$	$\text{V}_{\text{GS}}=20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	—	—	100	nA
Gate-Body Leakage Current,Reverse	$\text{I}_{\text{GSSR}}$	$\text{V}_{\text{GS}}=-20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	—	—	-100	nA
<b>On Characteristics</b>						
Gate-Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2	—	4	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=20\text{A}$	—	5.2	6.5	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $f=1.0\text{MHz}$	—	3374	—	pF
Output Capacitance	$\text{C}_{\text{oss}}$		—	507	—	pF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		—	18	—	pF
<b>Switching Characteristics</b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$\text{V}_{\text{DD}}=40\text{V}, \text{R}_G=20\Omega,$ $\text{V}_{\text{GS}}=10\text{V}$	—	37	—	ns
Turn-On Rise Time	$t_r$		—	30	—	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$		—	37	—	ns
Turn-Off Fall Time	$t_f$		—	20	—	ns
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=20\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$	—	67	—	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		—	19	—	nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		—	20	—	nC
<b>Drain-Source Body Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage	$\text{V}_{\text{SD}}$	$\text{I}_S=20\text{A}, \text{V}_{\text{GS}}=0\text{V}$	—	—	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$\text{I}_F=30\text{A},$ $d\text{I}_F/dt=100\text{A/us}$	—	48	—	ns
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		—	115	—	nC

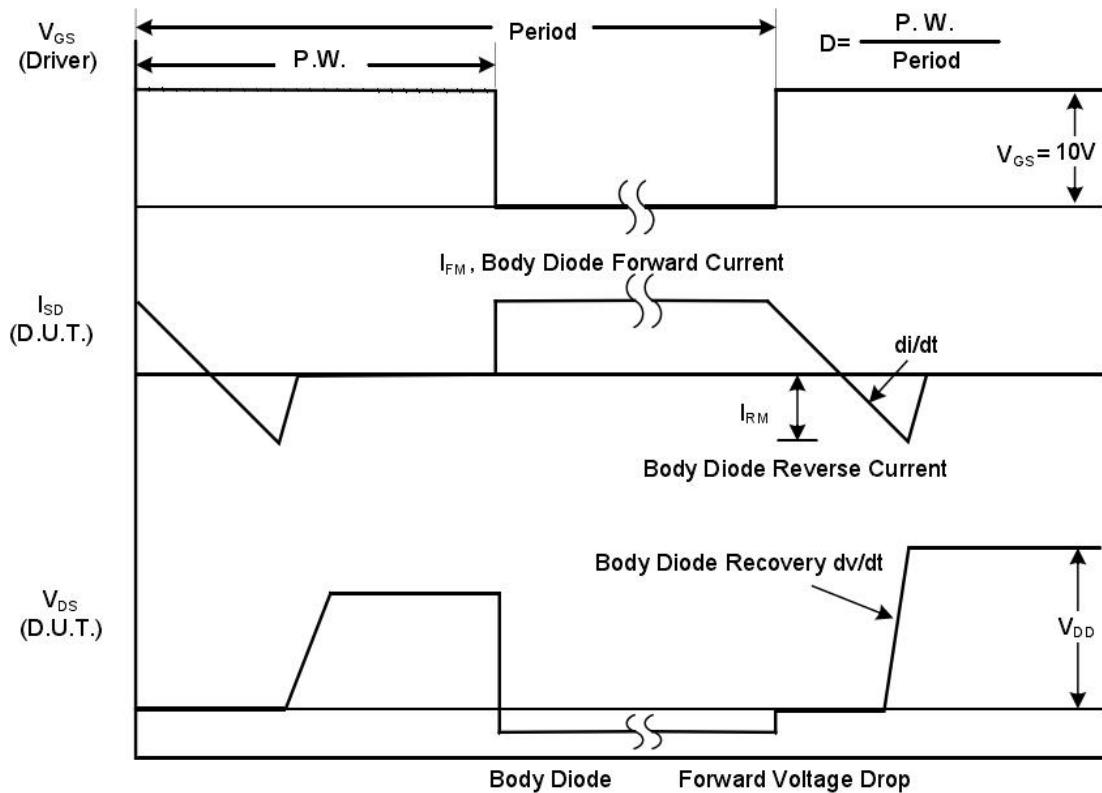
### Notes

- Repetitive Rating:pulse width limited by maximum junction temperature.
- $L=0.5\text{mH}, R_g=25\Omega$ , starting  $T_J=25^\circ\text{C}$ .
- Pulse width $\leq 300\text{us}$ ;duty cycle $\leq 2\%$ .

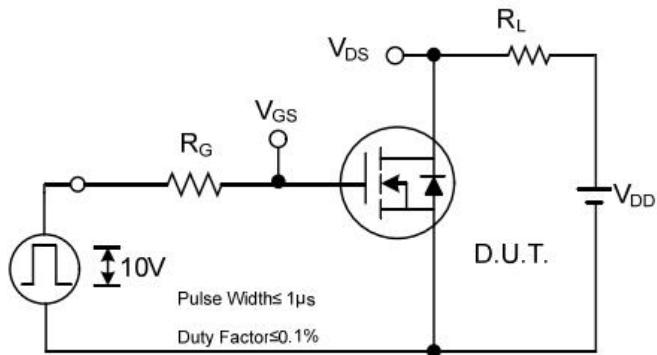
## RATING AND CHARACTERISTIC CURVES



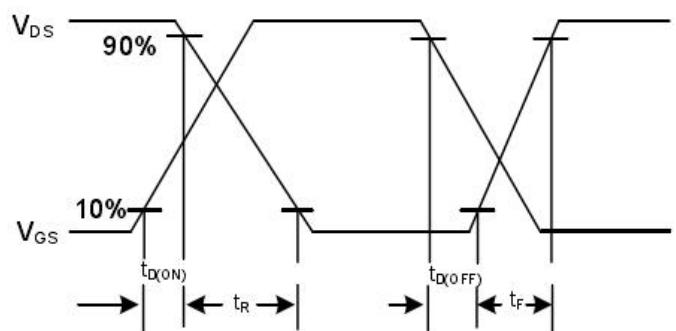
Peak Diode Recovery dv/dt Test Circuit



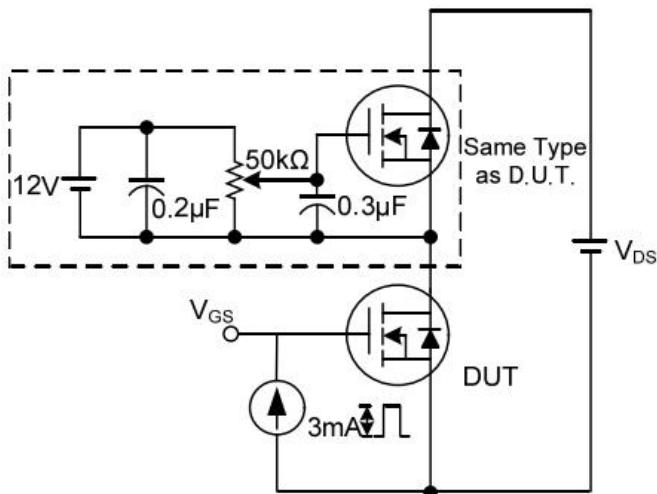
Peak Diode Recovery dv/dt Waveforms



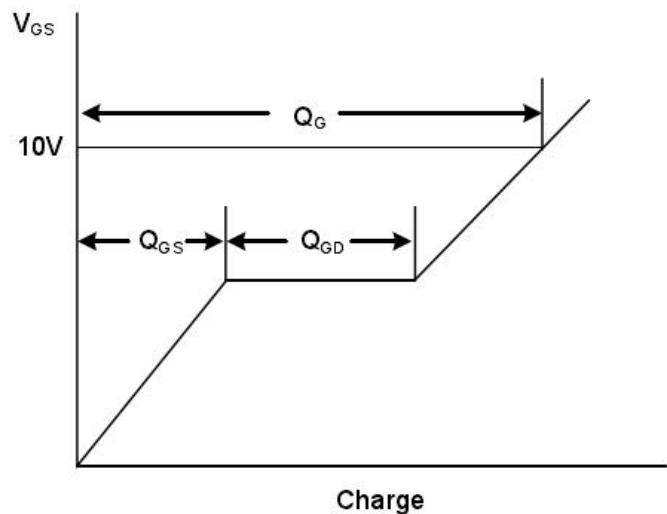
Switching Test Circuit



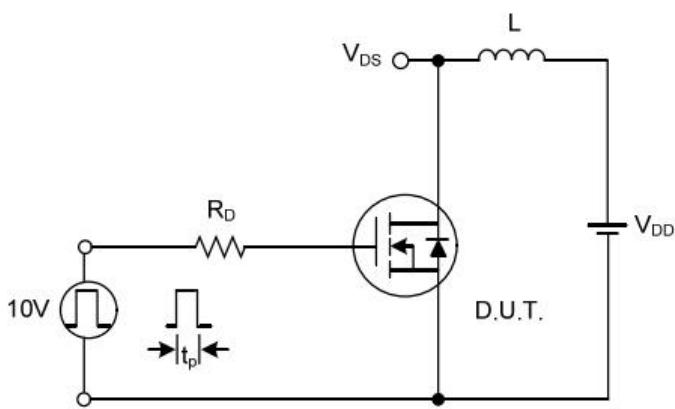
Switching Waveforms



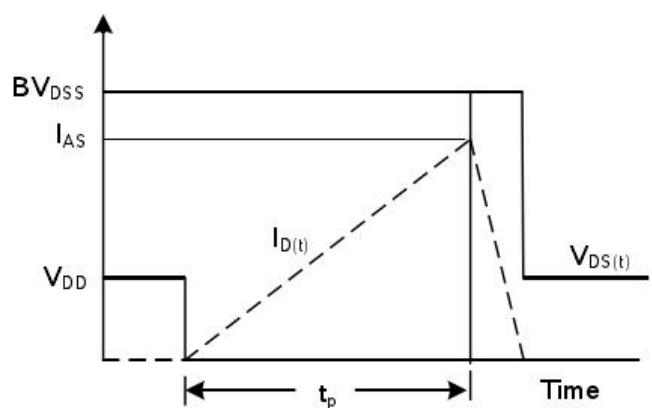
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

## RATING AND CHARACTERISTIC CURVES

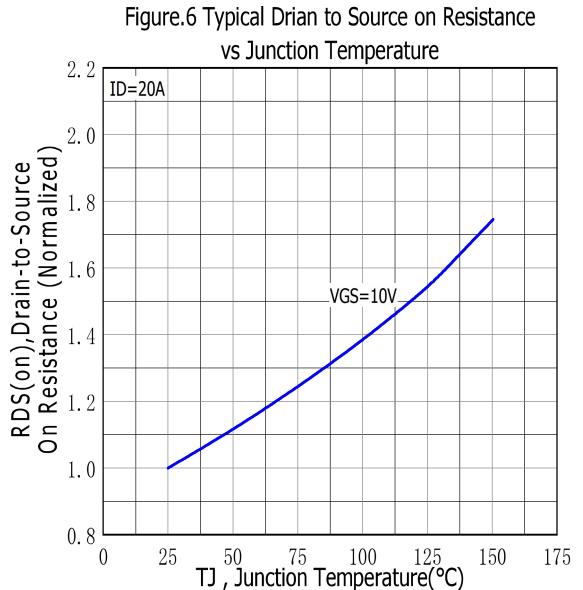
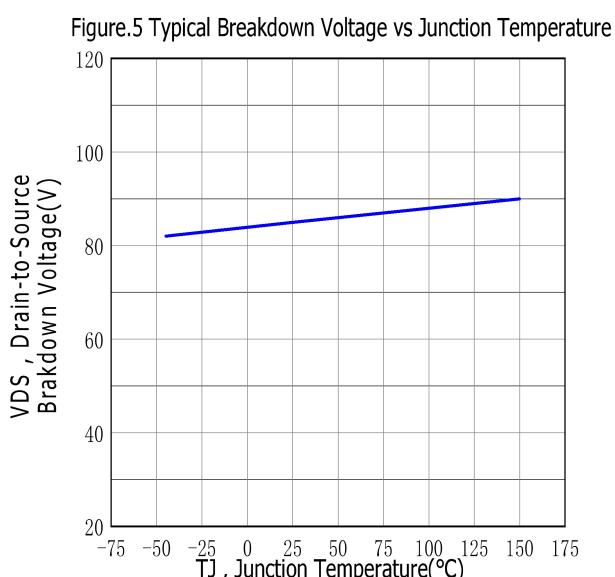
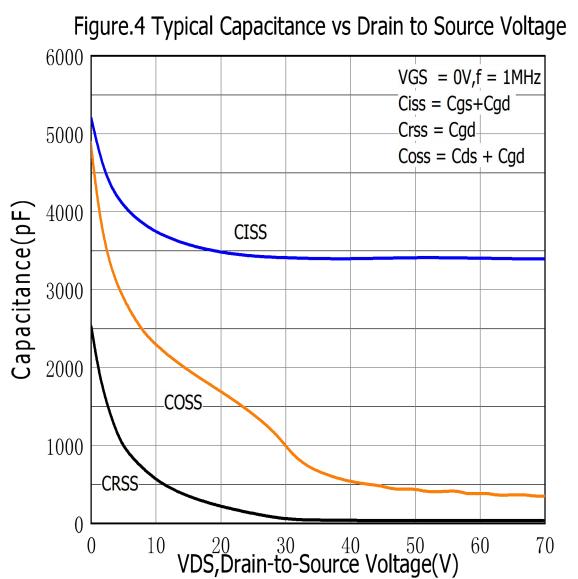
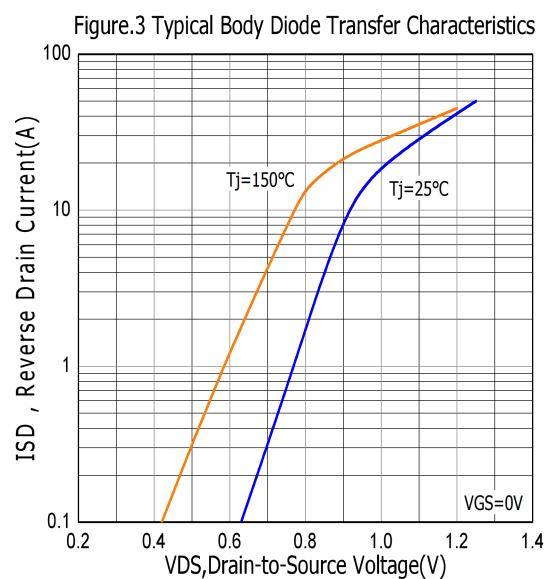
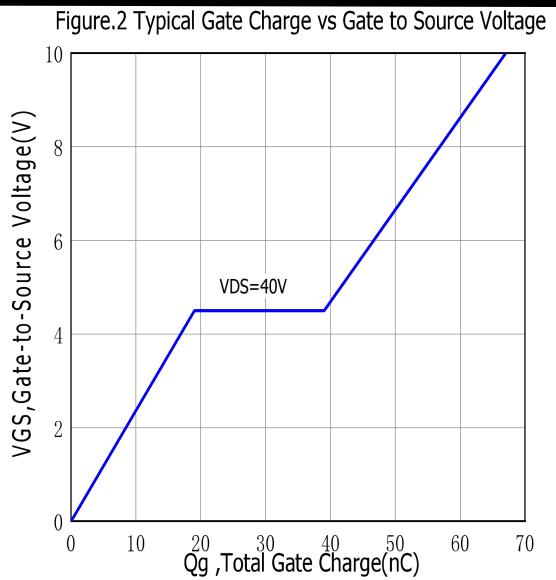
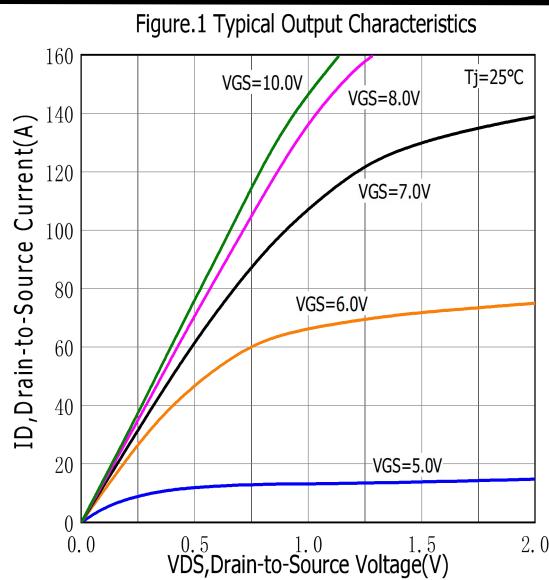


Figure.7 Maximum Forward Bias Safe Operating Area

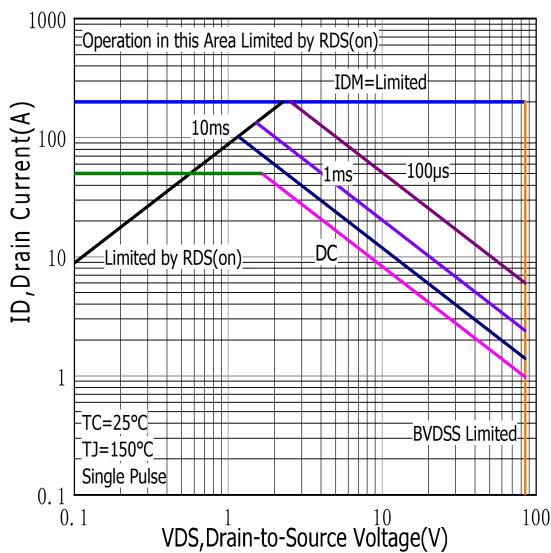


Figure.9 Maximum EAS vs Channel Temperature

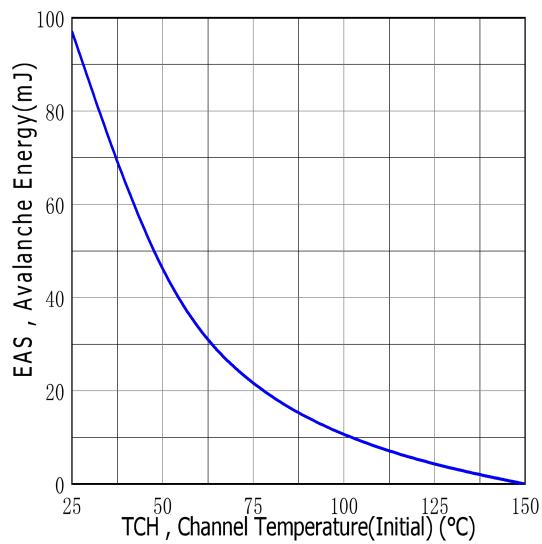


Figure.11 Maximum Effective Thermal Impedance , Junction to Case

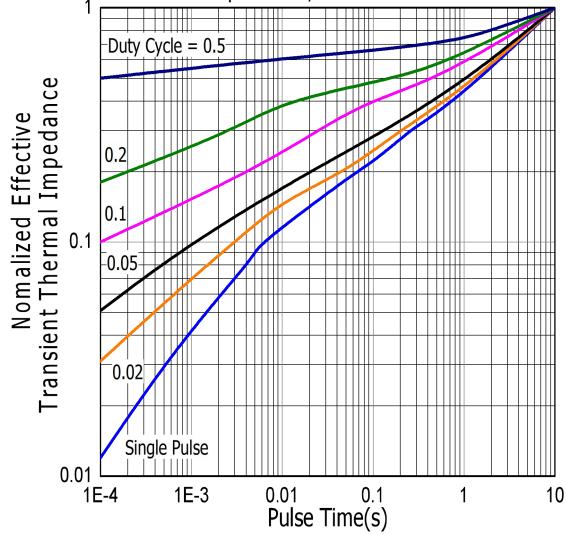


Figure.8 Typical Drain to Source ON Resistance vs Drain Current

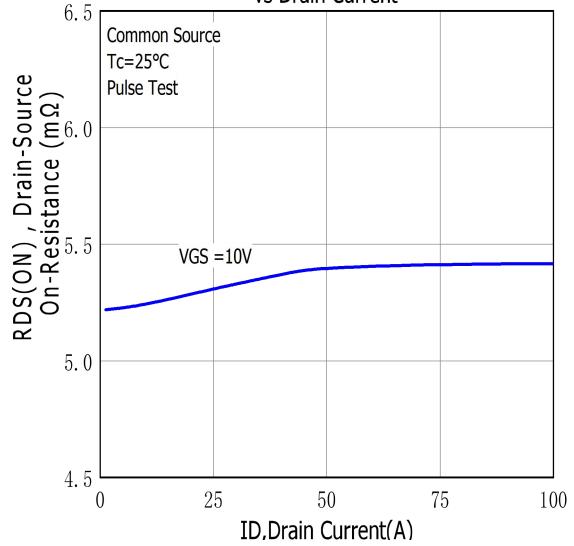


Figure.10 Typical Threshold Voltage vs Case Temperature

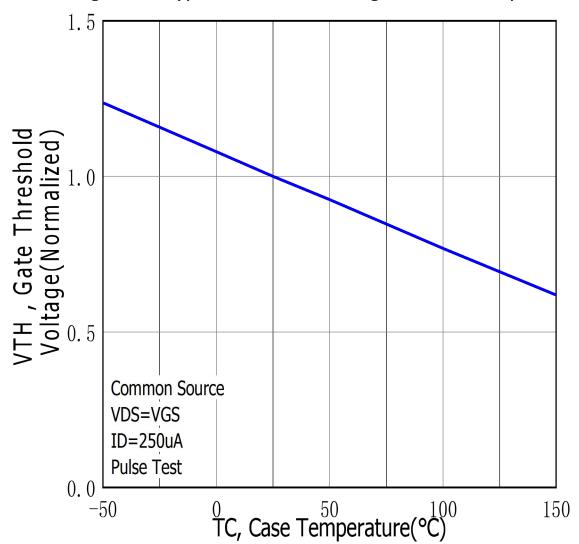
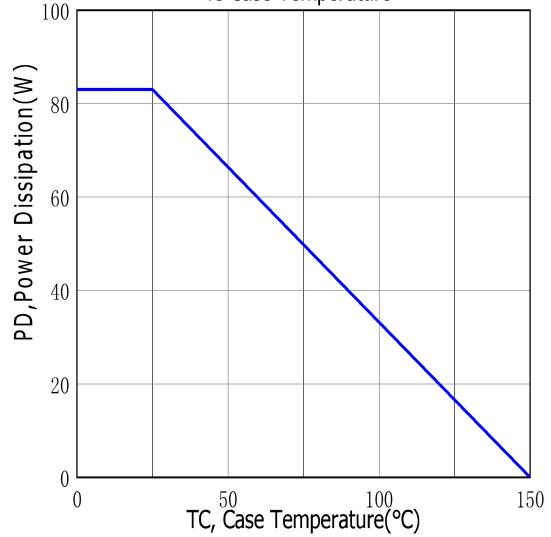
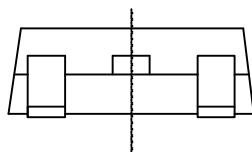
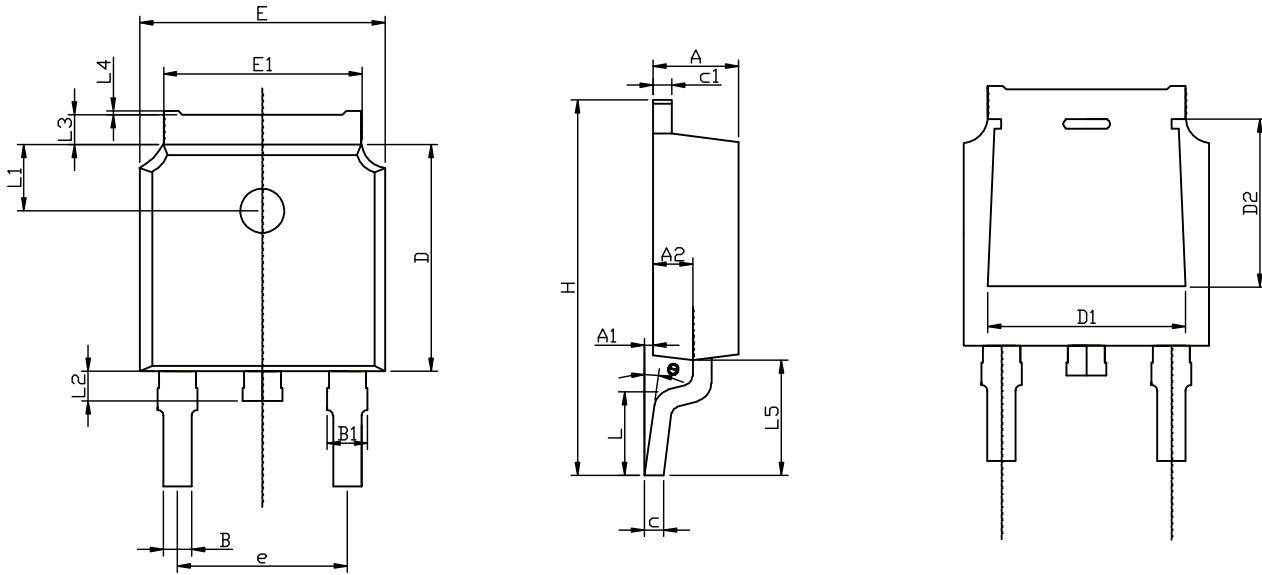


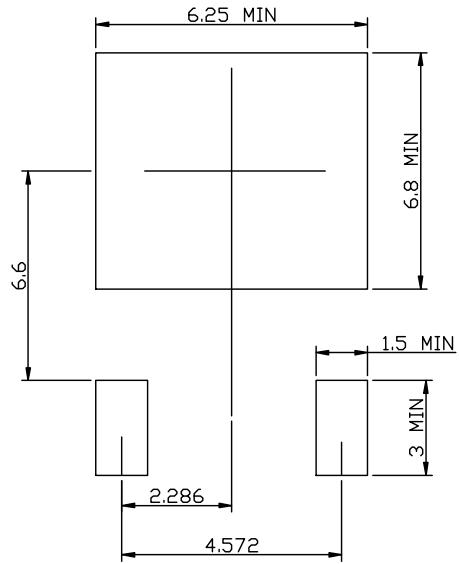
Figure.12 Maximum Power Dissipation vs Case Temperature



## TO-252-2L PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



	MIN	NOM	MAX
A	2.15	2.30	2.45
A1	0.05	0.10	0.20
A2	0.91	1.07	1.22
B	0.66	0.76	0.86
B1	0.93	1.08	1.23
C	0.40	0.50	0.60
C1	0.40	0.50	0.60
D	5.95	6.10	6.25
D1	—	4.8REF	—
D2	—	3.8REF	—
E	6.45	6.60	6.75
E1	5.12	5.32	5.52
L		1.65	
L1	1.58	1.78	1.98
L2	0.60	0.80	1.00
L3	0.70	0.85	1.00
L4	0.00	0.05	0.20
L5	2.80	3.10	3.40
H	9.80	10.10	10.40
$\Theta$	0°		8°
e		4.572REF	

UNIT: mm